Compliant with IEC 62474/ D9.00 Compliant to IEC 61249-2-21:2003

AICROCHIP Semiconductor Device Type:	6XX	6XX 128 TQFP 14x14x1mm Matte Tin		Termination Base Alloy: Copper Alloy (Cu)			Package Homogeneous Materials			
Basic Substance	CAS Number	"Contained In" Sub-Component	% Total Weight	mg/part	ppm	372.52	(mg) Total	Mold Compound	% ot Total Weight	66.82
Fused Silica	60676-86-0	Mold Compound	59.136	329.682	591.357		Fused Silica	60676-86-0	88.50	
Epoxy Resin	Trade Secret	Mold Compound	4.343	24.214	43,433		Epoxy Resin	Trade Secret	6.50	
Phenol Resin	Trade Secret	Mold Compound	3.174	17.695	31,740	1	Phenol Resin	Trade Secret	4.75	
Carbon Black	1333-86-4	Mold Compound	0.167	0.931	1,671	1	Carbon Black	1333-86-4	0.25	
Copper	7440-50-8	Lead Frame	25.658	143.043	256,579	1 '		Total	100.00	
Nickel	7440-02-0	Lead Frame	0.684	3.815	6,843	150.19	(mg) Total	Lead Frame	% of Total Weight	26.94
Silver	7440-22-4	Lead Frame	0.450	2.507	4,496	i i	Copper	7440-50-8	95.24	
Silicon	7440-21-3	Lead Frame	0.121	0.676	1,212	1	Nickel	7440-02-0	2.54	
Magnesium	7439-95-4	Lead Frame	0.027	0.150	269	1	Silver	7440-22-4	1.67	
Silver	7440-22-4	Die Attach	0.059	0.328	588	1	Silicon	7440-21-3	0.45	
Epoxy Resin	Trade secret	Die Attach	0.011	0.062	112	1	Magnesium	7439-95-4	0.10	
Silicon	7440-21-3	Chip (Die)	4.760	26.537	47,600	1 '	•	Total	100.00	
Copper	7440-50-8	Wire Bond Copper palladium coated (CuPd)	0.246	1.369	2,456	0.39	(mg) Total	Die Attach	% of Total Weight	0.07
Palladium	7440-05-3	Wire Bond Copper palladium coated (CuPd)	0.004	0.024	44		Silver	7440-22-4	84.00	
Tin	7440-31-5	Plating on external leads (pins) - Matte Tin / annealed at 150°C for 1 hour	1.160	6.467	11,600	1	Epoxy Resin	Trade secret	16.00	
	•	TOTALS:	100.000	557.500	1,000,000	1 '		Total	100.00	
	0.5575	g Total Mass			,,	26.54	Total (mg)	Chip (Die)	% of Total Weight	4.76
asmissandustan davias and its hamananana matadala assurbur			1 luna 2011\ av	- 1 004 F/000/FI	1704 Manali	20.0	rotal (mg)	G.i.p (2.6)	70 01 10ta. 110.g.u	
i) and 2000/53/EC and 2016/774/EU (End-of-Life Vehicles (ELV) w	ithout exemption	(zero)	5 June 2011) ar	10 2015/863/EC	J (31 March		Doped Silicon	7440-21-3 Total	100.00 100.00	
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i) and 2000/53/EC and 2016/774/EU (End-of-Life Vehicles (ELV) was pliance with the above EU Directives has been verified via interrection and substance is absent from the list above, the chemical suporated's knowledge and belief as of the date of this document is not below the threshold of regulatory concern for any regulating compounds used by Microchip meet the UL94 V0 flammabils://ul.com/global/eng/pages/offerings/industries/chemicals/plastic	ithout exemption nal design contro ubstance is NOT , there is no cred ory scheme worl ity standard for p	(zero) Is, supplier declarations, and /or analytical test data. an intentional ingredient in the semiconductor device and, ible reason to believe that the unavoidable impurity concerd-wide. Islastics. You can access the UL iQTM family of databases to	to the best of other of the oobtain a test	Microchip Tec chemical subs	chnology stance, if	1.39	·	Total Wire Bond Copper palladium	100.00	0.25
5) and 2000/53/EC and 2016/774/EU (End-of-Life Vehicles (ELV) w mpliance with the above EU Directives has been verified via intert chemical substance is absent from the list above, the chemical s orporated's knowledge and belief as of the date of this document, is not below the threshold of regulatory concern for any regulat ding compounds used by Microchip meet the UL94 V0 flammabil oz/ul.com/global/eng/pages/offerings/industries/chemicals/plastic protective "tubes" in which the specific product is shipped are r	ithout exemption nal design contro ubstance is NOT , there is no cred ory scheme worl ity standard for p	(zero) Is, supplier declarations, and /or analytical test data. an intentional ingredient in the semiconductor device and, ible reason to believe that the unavoidable impurity concerd-wide. Islastics. You can access the UL iQTM family of databases to	to the best of other of the oobtain a test	Microchip Tec chemical subs	chnology stance, if	1.39	(mg) Total	Total Wire Bond Copper palladium coated (CuPd) 7440-50-8 7440-05-3	98.25	0.25
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